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Form PTO 1449 (Modified)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY DOCKET NO. 278591US0PCT	SERIAL NO. 10/549,848
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT Atsushi IWATA, et al.	
		FILING DATE September 19, 2005	GROUP 1792

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

EXAMINER		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	TRANSLATION NO
/F.H./	AO	55-056004	04/24/80	JP (with English abstract)		NO
/F.H./	AP	58-204809	11/29/83	JP (with English abstract)		NO
	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

/F.H./	AW	AKEWATASHI, Jun et al., Ceramic Thin Film Formation Technology Using Collision and Solidification Phenomena of Particles and Ultra-fine Particles.- Aerosol Deposition Method for High Speed Coating at Low Temperature, National Institute of Advanced Industrial Science and Technology, Tsukuba, Pages 459 - 466, 2002, with Partial English Translation.
/F.H./	AX	KIM, I.W. et al., Critical Thickness for Transformation of Epitaxially Stabilized Cubic AIN in Superlattices, Applied Physics Letters, Vol. 78, No. 7, Pages 892 - 894, 2001.
/F.H./	AY	MASHIMO, Tsutomu et al., Yield Properties, Phase Transition, and equation of State of Aluminum Nitride (AIN) Under Shock Compression up to 150 GPa., Journal of Applied Physics, Vol. 86, No. 12, Pages 6710 - 6716, 1999.
	AZ	☐ Additional References sheet(s) attached

Examiner /Felisa Hiteshew/	Date Considered 04/18/2008

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /F.H./